



Telink

Telink Semiconductor (Shanghai) CO., LTD
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Composition Table

To: TELINK SEMICONDUCTOR (SHANGHAI) CO., LTD.

From: HuaTian Technology (Xi An) Co.,Ltd

Product Name: TLSR8251F512ET24

Weight(Unit): 38.2000 mg

Date: 2023/10/17

	Material name	Vendor	Weight(mg)	Substance Name	CAS No	Weight(mg)	Content (%) Substance	Content (%) Whole chip	Content (ppm)
Die1	Telink Die	SMIC BJ	1.5240	Silicon	7440-21-3	1.5240	100.00%	3.99%	1000000
Die2	GD Die	SMIC BJ	0.2760	Silicon	7440-21-3	0.2760	100.00%	0.72%	1000000
Lead Frame	A194	AAMI	11.9000					52.45%	
				Cu	7440-50-8	11.5192	96.80%	30.15%	968000
				Fe	7439-89-6	0.2737	2.30%	0.72%	23000
				Pb	7439-92-1	0.0012	0.01%	0.00%	100
				P	7723-14-0	0.0167	0.14%	0.04%	1400
				Zn	7440-66-6	0.0179	0.15%	0.05%	1500
				Aq	7440-22-4	0.0714	0.60%	0.19%	6000
DAF	ATB-120U	Henkel	0.9000					0.06%	
				Modified Epoxy Resin	Proprietary	0.5400	60.0%	1.41%	600000
				Synthetic resin	Proprietary	0.0855	9.5%	0.22%	95000
				Epoxy resin	Proprietary	0.1395	15.5%	0.22%	155000
				Dapsone	80-08-0	0.0450	5.0%	0.12%	50000
				Treated fumed silica	67762-90-7	0.0450	5.0%	0.12%	50000
Epoxy	L1-403NCA	LEGEND	0.9000					0.74%	
				Diethylene glycol monoethyl ether acetate	112-15-2	0.0900	10.00%	0.24%	100000
				Silica	15468-32-3	0.5400	60.00%	1.41%	600000
				Acylate resin	Proprietary	0.1350	15.00%	0.35%	150000
				Epoxy resin	Proprietary	0.1260	14.00%	0.33%	140000
				Peroxide	Proprietary	0.0090	1.00%	0.02%	10000
Wire	HS-ES5	Heesung	1.8000					0.43%	
				Silver:Wire	7440-22-4	1.7098	94.9900%	4.48%	949900
				Gold	7440-57-5	0.0090	0.5000%	0.02%	5000
				Palladium	7440-05-3	0.0810	4.5000%	0.21%	45000
Mold Compound	CEL-9220HF	RESONAC Materials	19.1000					43%	
				Epoxy Resin 1	Trade secret	0.0955	0.50%	0.25%	5000
				Epoxy Resin 2	Trade secret	0.0955	0.50%	0.25%	5000
				Epoxy Resin 3	Trade secret	0.0955	0.50%	0.25%	5000
				Hardener	Trade secret	0.3820	2.00%	1.00%	20000
				Catalyst	Trade secret	0.0019	0.01%	0.01%	100
				Carbon black	1333-86-4	0.0382	0.20%	0.10%	2000
				Amorphous silica1	60676-86-0	16.9589	88.79%	44.40%	887900
				Amorphous silica2	7631-86-9	1.4325	7.50%	3.75%	75000
Plating	TIN	AISEN	1.8000					2.07%	
				Tin	7440-31-5	1.7998	99.99%	4.71%	999900
Total			38.2000	Others	Trade Secret	0.0002	0.01%	0.00%	100
							100%		1000000

保存年限: 三年
OS1-A1
保存单位: QRA

文件编号: TFM-QRA-